

HVC397C

Variable Capacitance Diode for VCO

REJ03G0021-0100
(Previous: ADE-208-1561)
Rev.1.00
Apr.25.2003

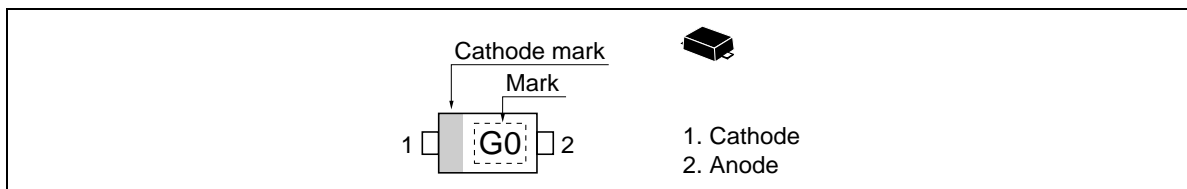
Features

- High capacitance ratio. ($n = 2.9$ min)
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC397C	G0	UFP

Pin Arrangement



HVC397C

Absolute Maximum Ratings

(Ta = 25°C)

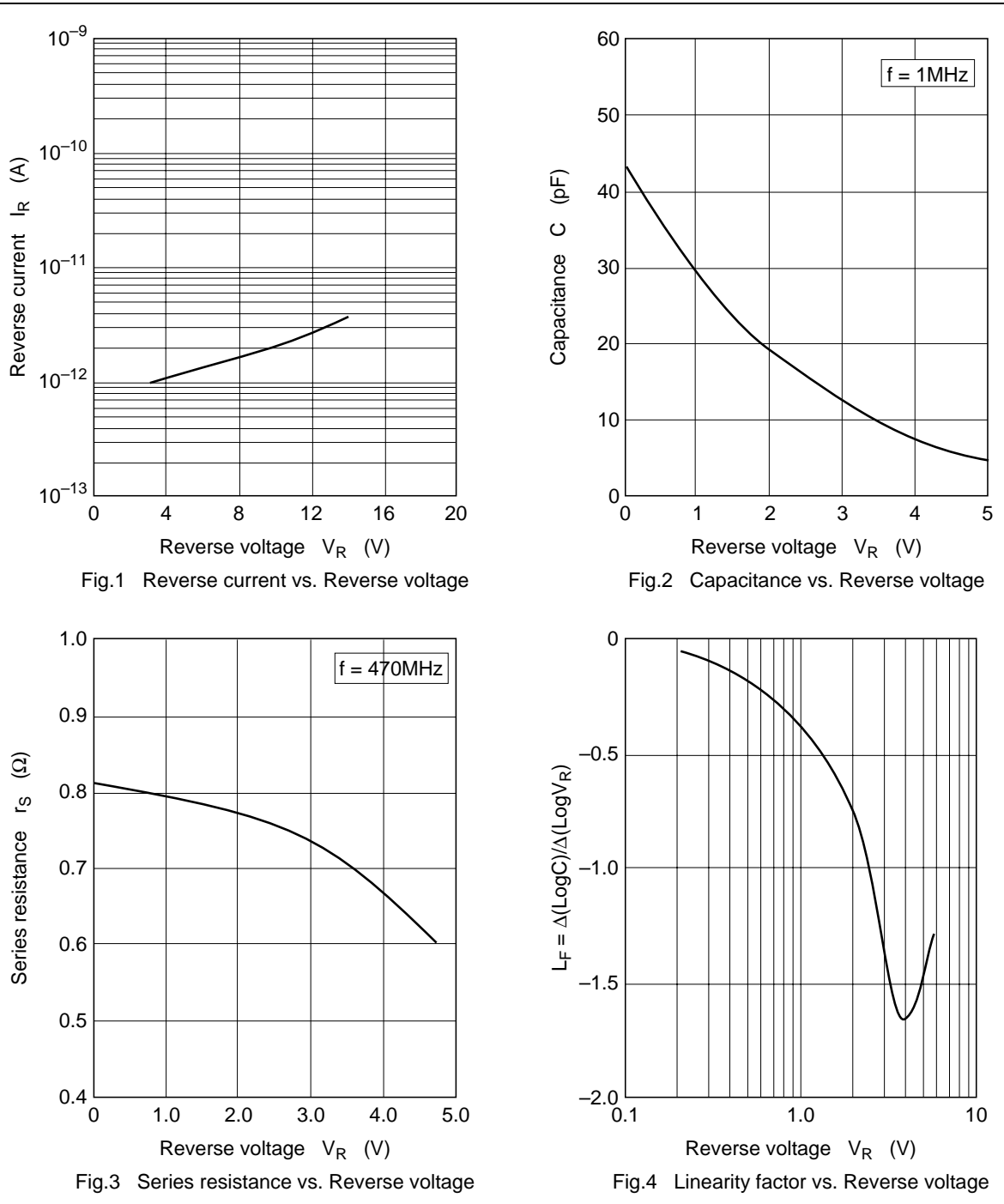
Item	Symbol	Value	Unit
Reverse voltage	V_R	15	V
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

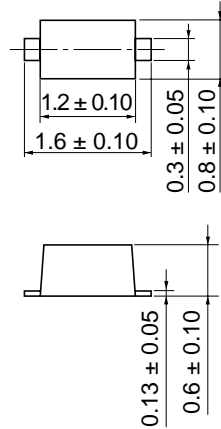
Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_{R1}	—	—	10	nA	$V_R = 10\text{ V}$
	I_{R2}	—	—	50		$V_R = 10\text{ V}, T_a = 60^\circ\text{C}$
Capacitance	C_1	27.0	—	28.5	pF	$V_R = 1\text{ V}, f = 1\text{ MHz}$
	C_2	18.0	—	20.0		$V_R = 2\text{ V}, f = 1\text{ MHz}$
	C_4	6.8	—	8.5		$V_R = 4\text{ V}, f = 1\text{ MHz}$
Capacitance ratio	n_1	1.3	—	—	—	C_1 / C_2
	n_2	2.9	—	—	—	C_1 / C_4
Series resistance	r_s	—	—	1.2	Ω	$V_R = 1\text{ V}, f = 470\text{ MHz}$

Main Characteristic



Package Dimensions

As of January, 2003
Unit: mm



Package Code	UFP
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.0016 g

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Keep safety first in your circuit designs!

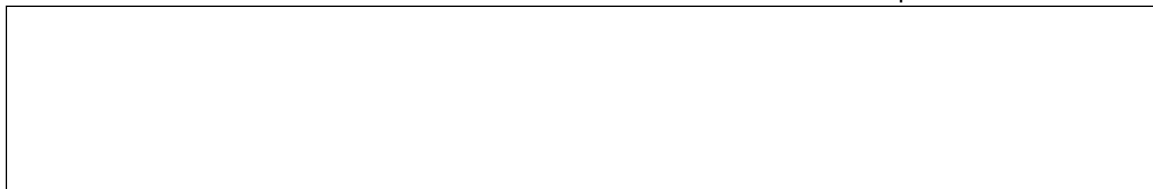
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